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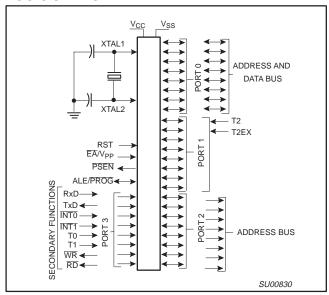
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	16MHz
Connectivity	EBI/EMI, UART/USART
Peripherals	POR, PWM
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p87c51fa-5a-512

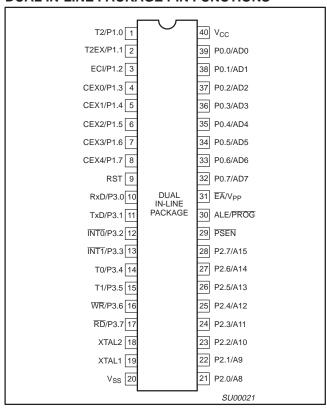
80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33 MHz) 8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

#### LOGIC SYMBOL

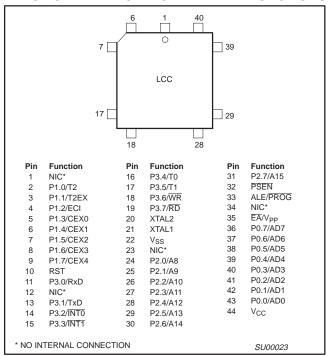


### **PIN CONFIGURATIONS**

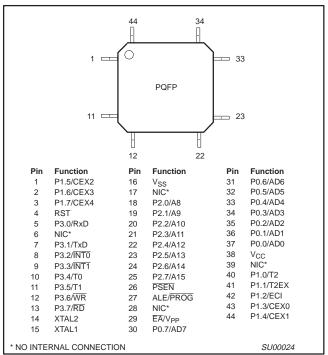
# **DUAL IN-LINE PACKAGE PIN FUNCTIONS**



#### PLASTIC LEADED CHIP CARRIER PIN FUNCTIONS



# PLASTIC QUAD FLAT PACK PIN FUNCTIONS



80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33 MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

# PIN DESCRIPTIONS (Continued)

	PII	N NUMB	ER		
MNEMONIC	DIP	LCC	QFP	TYPE	NAME AND FUNCTION
PSEN	29	32	26	0	Program Store Enable: The read strobe to external program memory. When executing code from the external program memory, $\overline{PSEN}$ is activated twice each machine cycle, except that two $\overline{PSEN}$ activations are skipped during each access to external data memory. $\overline{PSEN}$ is not activated during fetches from internal program memory.
ĒĀ/V <sub>PP</sub>	31	35	29	ı	External Access Enable/Programming Supply Voltage: $\overline{EA}$ must be externally held low to enable the device to fetch code from external program memory locations starting with 0000H. If $\overline{EA}$ is held high, the device executes from internal program memory unless the program counter contains an address greater than 8k Devices (IFFFH), 16k Devices (3FFFH) or 32k Devices (7FFFH). Since the RD+ has 64k Internal Memory, the RD+ will execute only from internal memory when $\overline{EA}$ is held high. This pin also receives the 12.75 V programming supply voltage (V <sub>PP</sub> ) during EPROM programming. If security bit 1 is programmed, $\overline{EA}$ will be internally latched on Reset.
XTAL1	19	21	15	ı	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	0	Crystal 2: Output from the inverting oscillator amplifier.

# NOTE:

To avoid "latch-up" effect at power-on, the voltage on any pin at any time must not be higher than  $V_{CC}$  + 0.5 V or  $V_{SS}$  – 0.5 V, respectively.

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8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

# **8XC54/58 ORDERING INFORMATION**

	MEMORY SIZE 16K×8	MEMORY SIZE 32K×8	TEMPERATURE RANGE °C AND PACKAGE	VOLTAGE RANGE	FREQ. (MHz)	DWG. #
ROM	P80C54SBPN	P80C58SBPN	0 to +70, Plastic Dual In-line Package	2.7 V to	0 to 16	SOT129-1
OTP	P87C54SBPN	P87C58SBPN	0 to +70, Flastic Dual III-lille Fackage	5.5 V	0 10 10	301129-1
ROM	P80C54SBAA	P80C58SBAA	0 to +70, Plastic Leaded Chip Carrier	2.7 V to	0 to 16	SOT187-2
OTP	P87C54SBAA	P87C58SBAA	0 to +70, Plastic Leaded Chip Carrier	5.5 V	0 10 16	301107-2
ROM	P80C54SBBB	P80C58SBBB	0 to +70, Plastic Quad Flat Pack	2.7 V to	0 to 16	SOT307-2
OTP	P87C54SBBB	P87C58SBBB	0 to +70, Flastic Quad Flat Fack	5.5 V	0 10 10	301301-2
ROM	P80C54SFPN	P80C58SFPN	-40 to +85, Plastic Dual In-line Package	2.7 V to	0 to 16	SOT129-1
OTP	P87C54SFPN	P87C58SFPN	-40 to +65, Flastic Dual III-lille Fackage	5.5 V	0 10 10	301129-1
ROM	P80C54SFA A	P80C58SFA A	-40 to +85, Plastic Leaded Chip Carrier	0 to 16	SOT187-2	
OTP	P87C54SFA A	P87C58SFA A	-40 to +65, Flastic Leaded Chip Camer	5.5 V	0 10 10	301107-2
ROM	P80C54SFBB	P80C58SFBB	–40 to +85, Plastic Quad Flat Pack	2.7 V to	0 to 16	SOT307-2
OTP	P87C54SFBB	P87C58SFBB	-40 to 703, Flastic Quad Flat Fack	5.5 V	0 10 10	301301-2
ROM	P80C54UBAA	P80C58UBAA	0 to +70, Plastic Leaded Chip Carrier	5 V	0 to 33	SOT187-2
OTP	P87C54UBAA	P87C58UBAA	0 to +70, Plastic Leaded Chip Carrier	5 V	0 10 33	301107-2
ROM	P80C54UBPN	P80C58UBPN	0 to +70, Plastic Dual In-line Package	5 V	0 to 33	SOT129-1
OTP	P87C54UBPN	P87C58UBPN	0 to +70, Flastic Dual III-IIIIe Fackage	J V	0 10 33	301129-1
ROM	P80C54UBBB	P80C58UBBB	0 to +70, Plastic Quad Flat Pack	5 V	0 to 33	SOT307-2
OTP	P87C54UBBB	P87C58UBBB	0 to +70, Flastic Quad Flat Fack	J V	0 10 33	301301-2
ROM	P80C54UFAA	P80C58UFA A	-40 to +85, Plastic Leaded Chip Carrier	5 V	0 to 33	SOT187-2
OTP	P87C54UFAA	P87C58UFA A	-40 to 405, Flastic Leaded Chip Camel	J 5 V	0 10 33	301107-2
ROM	P80C54UFPN	P80C58UFPN	40 to 105 Pleatia Puel la line Produce	5 V	0 to 33	SOT129-1
OTP	P87C54UFPN	P87C58UFPN	–40 to +85, Plastic Dual In-line Package	5 v	0 10 33	301129-1
ROM	P80C54UFBB	P80C58UFBB	–40 to +85, Plastic Quad Flat Pack	5 V	0 to 33	SOT307-2
OTP	P87C54UFBB	P87C58UFBB	-40 to 400, Flastic Quau Flat Pack	5 V	0 10 33	301307-2

Note: For Multi Time Programmable devices, See P89C51RX+

Flash datasheet.

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Table 2. 8XC51FA/FB/FC, 8XC51RA+/RB+/RC+/RD+ Special Function Registers (Continued)

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT A	ADDRESS	, SYMBO	L, OR AL	TERNATIV	E PORT	FUNCTIO	N LSB	RESET VALUE
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program Status Word	D0H	CY	AC	F0	RS1	RS0	OV	_	Р	000000x0B
RACAP2H#	Timer 2 Capture High	СВН									00H
RACAP2L#	Timer 2 Capture Low	CAH									00H
SADDR#	Slave Address	A9H									00H
SADEN#	Slave Address Mask	В9Н									00H
SBUF	Serial Data Buffer	99H									xxxxxxxxB
			9F	9E	9D	9C	9B	9A	99	98	
SCON*	Serial Control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SP	Stack Pointer	81H									07H
			8F	8E	8D	8C	8B	8A	89	88	
TCON*	Timer Control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00H
			CF	CE	CD	СС	СВ	CA	C9	C8	
T2CON*	Timer 2 Control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2	00H
T2MOD#	Timer 2 Mode Control	C9H	_	_	-	-	-	-	T2OE	DCEN	xxxxxx00B
TH0	Timer High 0	8CH									00H
TH1	Timer High 1	8DH									00H
TH2#	Timer High 2	CDH									00H
TL0	Timer Low 0	8AH									00H
TL1 TL2#	Timer Low 1 Timer Low 2	8BH CCH									00H 00H
LZ#	Timer LOW Z	ССП									UUII
TMOD	Timer Mode	89H	GATE	C/T	M1	M0	GATE	C/T	M1	M0	00H
WDTRST	HDW Watchdog Timer Reset (RX+ only)	0A6H									

 <sup>\*</sup> SFRs are bit addressable.

# **OSCILLATOR CHARACTERISTICS**

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

# **RESET**

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on  $V_{CC}$  and RST must come up at the same time for a proper start-up. Ports 1, 2, and 3 will asynchronously be driven to their reset condition when a voltage above  $V_{IH1}$  (min.) is applied to RESET.

<sup>#</sup> SFRs are modified from or added to the 80C51 SFRs.

Reserved bits.

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#### **LOW POWER MODES**

# **Stop Clock Mode**

The static design enables the clock speed to be reduced down to 0 MHz (stopped). When the oscillator is stopped, the RAM and Special Function Registers retain their values. This mode allows step-by-step utilization and permits reduced system power consumption by lowering the clock frequency down to any value. For lowest power consumption the Power Down mode is suggested.

#### Idle Mode

In the idle mode (see Table 3), the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

#### **Power-Down Mode**

To save even more power, a Power Down mode (see Table 3) can be invoked by software. In this mode, the oscillator is stopped and the instruction that invoked Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values down to 2.0V and care must be taken to return  $V_{CC}$  to the minimum specified operating voltages before the Power Down Mode is terminated.

Either a hardware reset or external interrupt can be used to exit from Power Down. Reset redefines all the SFRs but does not change the on-chip RAM. An external interrupt allows both the SFRs and the on-chip RAM to retain their values.

To properly terminate Power Down the reset or external interrupt should not be executed before  $V_{\rm CC}$  is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize (normally less than 10ms).

With an external interrupt, INT0 and INT1 must be enabled and configured as level-sensitive. Holding the pin low restarts the oscillator but bringing the pin back high completes the exit. Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put the device into Power Down.

#### **LPEP**

The LPEP bit (AUXR.4), only needs to be set for applications operating at  $V_{\rm CC}$  less than 4V.

#### POWER OFF FLAG

The Power Off Flag (POF) is set by on-chip circuitry when the  $V_{CC}$  level on the 8XC51FX/8XC51RX+ rises from 0 to 5V. The POF bit can be set or cleared by software allowing a user to determine if the reset is the result of a power-on or a warm start after powerdown. The  $V_{CC}$  level must remain above 3V for the POF to remain unaffected by the  $V_{CC}$  level.

#### **Design Consideration**

• When the idle mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

### **ONCE™ Mode**

The ONCE ("On-Circuit Emulation") Mode facilitates testing and debugging of systems without the device having to be removed from the circuit. The ONCE Mode is invoked by:

- 1. Pull ALE low while the device is in reset and PSEN is high;
- 2. Hold ALE low as RST is deactivated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and PSEN are weakly pulled high. The oscillator circuit remains active. While the device is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a normal reset is applied.

# **Programmable Clock-Out**

A 50% duty cycle clock can be programmed to come out on P1.0. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed:

- 1. to input the external clock for Timer/Counter 2, or
- to output a 50% duty cycle clock ranging from 61Hz to 4MHz at a 16MHz operating frequency.

To configure the Timer/Counter 2 as a clock generator, bit  $C/\overline{T}2$  (in T2CON) must be cleared and bit T20E in T2MOD must be set. Bit TR2 (T2CON.2) also must be set to start the timer.

The Clock-Out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L) as shown in this equation:

Oscillator Frequency 4 × (65536 - RCAP2H, RCAP2L)

Where (RCAP2H,RCAP2L) = the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

In the Clock-Out mode Timer 2 roll-overs will not generate an interrupt. This is similar to when it is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and the Clock-Out frequency will be the same.

Table 3. External Pin Status During Idle and Power-Down Mode

MODE	PROGRAM MEMORY	ALE	PSEN	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

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#### **TIMER 2 OPERATION**

#### Timer 2

Timer 2 is a 16-bit Timer/Counter which can operate as either an event timer or an event counter, as selected by C/T2\* in the special function register T2CON (see Figure 1). Timer 2 has three operating modes: Capture, Auto-reload (up or down counting), and Baud Rate Generator, which are selected by bits in the T2CON as shown in Table 4.

# **Capture Mode**

In the capture mode there are two options which are selected by bit EXEN2 in T2CON. If EXEN2=0, then timer 2 is a 16-bit timer or counter (as selected by C/T2\* in T2CON) which, upon overflowing sets bit TF2, the timer 2 overflow bit. This bit can be used to generate an interrupt (by enabling the Timer 2 interrupt bit in the IE register). If EXEN2= 1, Timer 2 operates as described above, but with the added feature that a 1-to-0 transition at external input T2EX causes the current value in the Timer 2 registers, TL2 and TH2, to be captured into registers RCAP2L and RCAP2H, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set, and EXF2 like TF2 can generate an interrupt (which vectors to the same location as Timer 2 overflow interrupt. The Timer 2 interrupt service routine can interrogate TF2 and EXF2 to determine which event caused the interrupt). The capture mode is illustrated in Figure 2. (There is no reload value for TL2 and TH2 in this mode. Even when a capture event occurs from T2EX, the counter keeps on counting T2EX pin transitions or osc/12 pulses.)

#### Auto-Reload Mode (Up or Down Counter)

In the 16-bit auto-reload mode, Timer 2 can be configured (as either a timer or counter  $[C/T2^*$  in T2CON]) then programmed to count up or down. The counting direction is determined by bit DCEN (Down Counter Enable) which is located in the T2MOD register (see

Figure 3). When reset is applied the DCEN=0 which means Timer 2 will default to counting up. If DCEN bit is set, Timer 2 can count up or down depending on the value of the T2EX pin.

Figure 4 shows Timer 2 which will count up automatically since DCEN=0. In this mode there are two options selected by bit EXEN2 in T2CON register. If EXEN2=0, then Timer 2 counts up to 0FFFFH and sets the TF2 (Overflow Flag) bit upon overflow. This causes the Timer 2 registers to be reloaded with the 16-bit value in RCAP2L and RCAP2H. The values in RCAP2L and RCAP2H are preset by software means

If EXEN2=1, then a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at input T2EX. This transition also sets the EXF2 bit. The Timer 2 interrupt, if enabled, can be generated when either TF2 or EXF2 are 1.

In Figure 5 DCEN=1, which enables Timer 2 to count up or down. This mode allows pin T2EX to control the direction of count. When a logic 1 is applied at pin T2EX Timer 2 will count up. Timer 2 will overflow at 0FFFFH and set the TF2 flag, which can then generate an interrupt, if the interrupt is enabled. This timer overflow also causes the 16-bit value in RCAP2L and RCAP2H to be reloaded into the timer registers TL2 and TH2.

When a logic 0 is applied at pin T2EX this causes Timer 2 to count down. The timer will underflow when TL2 and TH2 become equal to the value stored in RCAP2L and RCAP2H. Timer 2 underflow sets the TF2 flag and causes 0FFFFH to be reloaded into the timer registers TL2 and TH2.

The external flag EXF2 toggles when Timer 2 underflows or overflows. This EXF2 bit can be used as a 17th bit of resolution if needed. The EXF2 flag does not generate an interrupt in this mode of operation.

	(MSE	3)						(LSB)	
	Т	F2 EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2	
Symbol	Position	Name and Sig	nificance						
TF2	T2CON.7	Timer 2 overflowhen either RC			overflow and	d must be c	leared by so	oftware. TF2	will not be set
EXF2	T2CON.6	EXEN2 = 1. W interrupt routing	mer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and XEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 terrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down sounter mode (DCEN = 1).						
RCLK	T2CON.5	Receive clock in modes 1 and							r its receive clock
TCLK	T2CON.4	Transmit clock in modes 1 and							or its transmit clock.
EXEN2	T2CON.3	Timer 2 externation on Tailing ignore events a	EX if Time						
TR2	T2CON.2	Start/stop cont	ol for Time	r 2. A logic 1	starts the ti	mer.			
C/T2	T2CON.1		nternal time	r (OSĆ/12)	falling edge	triggered).			
CP/RL2	T2CON.0	cleared, auto-r	eloads will onen either F	occur either	with Timer 2	overflows	or negative t	ransitions at	ced to auto-reload
		on niner 2 ove	mow.						S

Figure 1. Timer/Counter 2 (T2CON) Control Register

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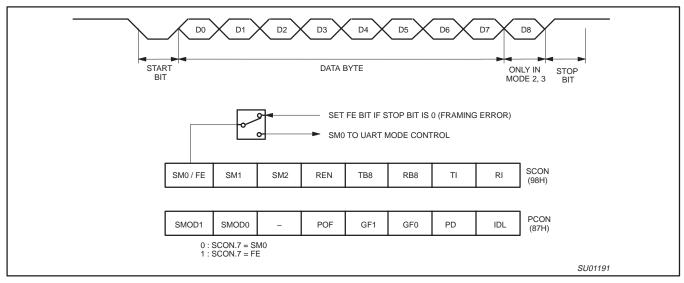


Figure 8. UART Framing Error Detection

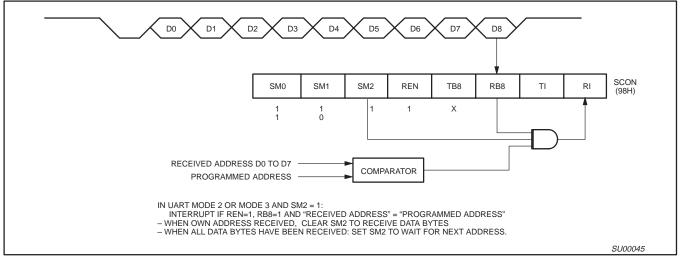


Figure 9. UART Multiprocessor Communication, Automatic Address Recognition

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#### **Interrupt Priority Structure**

The 8XC51FA/FB/FC and 8XC51RA+/RB+/RC+/RD+ have a 7-source four-level interrupt structure (see Table 8). The 80C54/58 have a 6-source four-level interrupt structure because these devices do not have a PCA.

There are 3 SFRs associated with the four-level interrupt. They are the IE, IP, and IPH. (See Figures 10, 11, and 12.) The IPH (Interrupt Priority High) register makes the four-level interrupt structure possible. The IPH is located at SFR address B7H. The structure of the IPH register and a description of its bits is shown in Figure 12.

The function of the IPH SFR is simple and when combined with the IP SFR determines the priority of each interrupt. The priority of each interrupt is determined as shown in the following table:

PRIOR	ITY BITS	INTERRUPT PRIORITY LEVEL					
IPH.x	IP.x	INTERRUPT PRIORITY LEVEL					
0	0	Level 0 (lowest priority)					
0	1	Level 1					
1	0	Level 2					
1	1	Level 3 (highest priority)					

The priority scheme for servicing the interrupts is the same as that for the 80C51, except there are four interrupt levels rather than two as on the 80C51. An interrupt will be serviced as long as an interrupt of equal or higher priority is not already being serviced. If an interrupt of equal or higher level priority is being serviced, the new interrupt will wait until it is finished before being serviced. If a lower priority level interrupt is being serviced, it will be stopped and the new interrupt serviced. When the new interrupt is finished, the lower priority level interrupt that was stopped will be completed.

Table 8. Interrupt Table

·				
SOURCE	POLLING PRIORITY	REQUEST BITS	HARDWARE CLEAR?	VECTOR ADDRESS
X0	1	IE0	N (L) <sup>1</sup> Y (T) <sup>2</sup>	03H
T0	2	TF0	Υ	0B
X1	3	IE1	N (L) Y (T)	13
T1	4	TF1	Υ	1B
PCA	5	CF, CCFn n = 0-4	N	33
SP	6	RI, TI	N	23
T2	7	TF2, EXF2	N	2B

#### NOTES:

- 1. L = Level activated
- 2. T = Transition activated

_	_	7	6	5	4	3	2	1	0
	IE (0A8H)	EA	EC	ET2	ES	ET1	EX1	ET0	EX0
			Bit = 1 ena Bit = 0 dis		nterrupt.				
BIT	SYMBOL	FUNC	TION						
IE.7	EA				0, all inter				each inte
IE.6	EC	PCA ir	nterrupt er	able bit fo	or FX and	RX+ only	- otherwi	se it is no	t impleme
IE.5	ET2	Timer	2 interrup	enable b	it.				
IE.4	ES	Serial	Port interr	upt enable	e bit.				
IE.3	ET1	Timer	1 interrup	enable b	it.				
IE.2	EX1	Extern	al interrup	t 1 enable	e bit.				
IE.1	ET0	Timer	0 interrup	enable b	it.				
IE.0	EX0	Extern	al interrup	t 0 enable	e bit.				

Figure 10. IE Registers

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8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

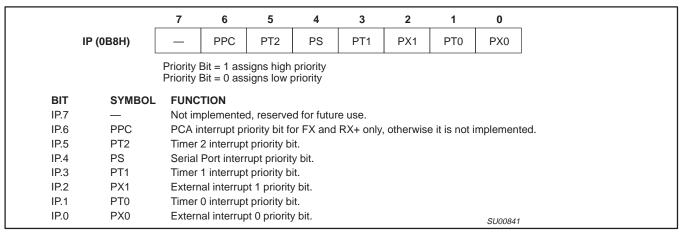


Figure 11. IP Registers

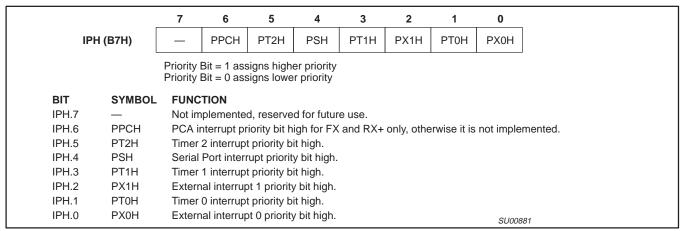


Figure 12. IPH Registers

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

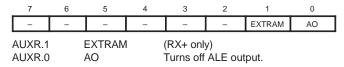
8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

#### Reduced EMI Mode

The AO bit (AUXR.0) in the AUXR register when set disables the ALE output.

#### **Reduced EMI Mode**

# AUXR (8EH)



#### **Dual DPTR**

The dual DPTR structure (see Figure 13) is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 that allows the program code to switch between them.

New Register Name: AUXR1#

SFR Address: A2H

Reset Value: xxxx00x0B



Where:

DPS = AUXR1/bit0 = Switches between DPTR0 and DPTR1.

Select Reg	DPS
DPTR0	0
DPTR1	1

The DPS bit status should be saved by software when switching between DPTR0 and DPTR1.

The GF3 bit is a general purpose user–defined flag. Note that bit 2 is not writable and is always read as a zero. This allows the DPS bit to

be quickly toggled simply by executing an INC DPTR instruction without affecting the GF3 or LPEP bits.

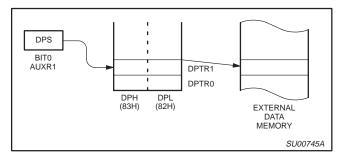


Figure 13.

#### **DPTR Instructions**

The instructions that refer to DPTR refer to the data pointer that is currently selected using the AUXR1/bit 0 register. The six instructions that use the DPTR are as follows:

INC DPTR	Increments the data pointer by 1
MOV DPTR, #data16	Loads the DPTR with a 16-bit constant
MOV A, @ A+DPTR	Move code byte relative to DPTR to ACC
MOVX A, @ DPTR	Move external RAM (16-bit address) to ACC
MOVX @ DPTR , A	Move ACC to external RAM (16-bit address)
JMP @ A + DPTR	Jump indirect relative to DPTR

The data pointer can be accessed on a byte-by-byte basis by specifying the low or high byte in an instruction which accesses the SFRs. See application note AN458 for more details.

# (8XC51FX and 8XC51RX+ ONLY)

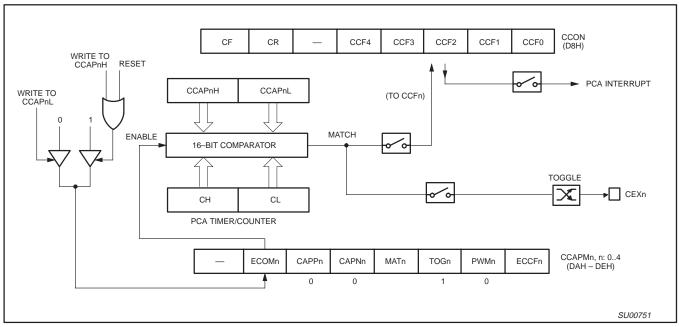


Figure 23. PCA High Speed Output Mode

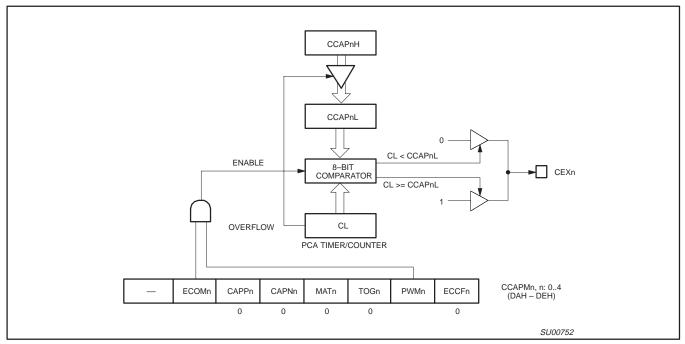


Figure 24. PCA PWM Mode

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

# (8XC51FX and 8XC51RX+ ONLY)

```
INIT_WATCHDOG:
  MOV CCAPM4, #4CH ; Module 4 in compare mode
MOV CCAP4L, #0FFH ; Write to low byte first
  MOV CCAP4H, #0FFH
                        ; Before PCA timer counts up to
                        ; FFFF Hex, these compare values
                        ; must be changed
  ORL CMOD, #40H
                        ; Set the WDTE bit to enable the
                        ; watchdog timer without changing
                        ; the other bits in CMOD
; Main program goes here, but CALL WATCHDOG periodically.
; ***********************
WATCHDOG:
  CLR EA ; Hold off interrupts
MOV CCAP4L, #00 ; Next compare value is within
  MOV CCAP4H, CH
                       ; 255 counts of the current PCA
  SETB EA
                        ; timer value
  RET
```

Figure 26. PCA Watchdog Timer Initialization Code

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

# (8XC51RX+ ONLY)

# Expanded Data RAM Addressing (8XC51RX+ ONLY)

The 8XC51RX+ have internal data memory that is mapped into four separate segments: the lower 128 bytes of RAM, upper 128 bytes of RAM, 128 bytes Special Function Register (SFR), and 256 bytes (768 for RD+) expanded RAM (EXTRAM).

The four segments are:

- The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- The 256-bytes (768 for RD+) expanded RAM ((EXTRAM (256-bytes) 00H–FFH)) and ((EXTRAM (768-bytes for RD+) 00H – 2FFH)) are indirectly accessed by move external instruction, MOVX, and with the EXTRAM bit cleared, see Figure 27.

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction. Instructions that use direct addressing access SFR space. For example:

#### MOV 0A0H,#data

accesses the SFR at location 0A0H (which is P2). Instructions that use indirect addressing access the Upper 128 bytes of data RAM.

# For example:

MOV @R0,#data

where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

The EXTRAM can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory is physically located on-chip, logically occupies the first 256-bytes (768 for RD+) of external data memory.

With EXTRAM = 0, the EXTRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. An access to EXTRAM will not affect ports P0, P3.6 (WR#) and P3.7 (RD#). P2 SFR is output during external addressing. For example, with EXTRAM = 0,

#### MOVX @R0,#data

where R0 contains 0A0H, access the EXTRAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (2FF for RD+) (i.e., 0100H to FFFFH) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address bus, and P3.6 and P3.7 as write and read timing signals. Refer to Figure 28.

With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an 8-bit address multiplexed with data on Port 0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a 16-bit address. Port 2 outputs the high-order eight address bits (the contents of DPH) while Port 0 multiplexes the low-order eight address bits (DPL) with data. MOVX @Ri and MOVX @DPTR will generate either read or write signals on P3.6 (#WR) and P3.7 (#RD).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the EXTRAM.

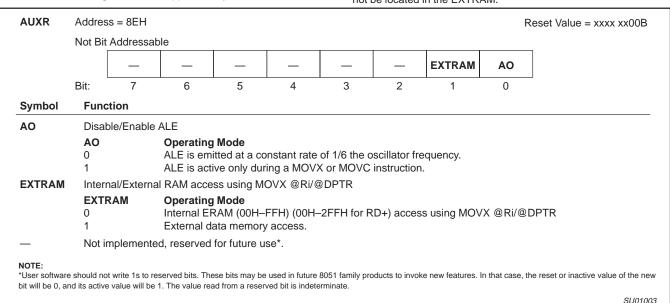


Figure 27. AUXR: Auxiliary Register (RX+ only)

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMIess, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

#### DC ELECTRICAL CHARACTERISTICS

 $T_{amb} = 0^{\circ}C$  to +70°C or -40°C to +85°C,  $V_{CC} = 2.7V$  to 5.5V,  $V_{SS} = 0V$  (16MHz devices)

CVMDC	DADAMETER	TEST				
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP <sup>1</sup>	MAX	UNIT
V	least less selfe re	4.0V < V <sub>CC</sub> < 5.5V	-0.5		0.2V <sub>CC</sub> -0.1	V
$V_{IL}$	Input low voltage	2.7V <v<sub>CC&lt; 4.0V</v<sub>	-0.5		0.7	V
V <sub>IH</sub>	Input high voltage (ports 0, 1, 2, 3, EA)		0.2V <sub>CC</sub> +0.9		V <sub>CC</sub> +0.5	V
V <sub>IH1</sub>	Input high voltage, XTAL1, RST		0.7V <sub>CC</sub>		V <sub>CC</sub> +0.5	V
V <sub>OL</sub>	Output low voltage, ports 1, 2 8	$V_{CC} = 2.7V$ $I_{OL} = 1.6 \text{mA}^2$			0.4	V
V <sub>OL1</sub>	Output low voltage, port 0, ALE, PSEN <sup>8, 7</sup>	$V_{CC} = 2.7V$ $I_{OL} = 3.2 \text{mA}^2$			0.4	V
V <sub>OH</sub> Output high voltage, ports 1, 2, 3 <sup>3</sup>	Output high walterns marks 4, 0, 0,3	V <sub>CC</sub> = 2.7V I <sub>OH</sub> = -20μA	V <sub>CC</sub> - 0.7			V
	Output nigh voltage, ports 1, 2, 3	V <sub>CC</sub> = 4.5V I <sub>OH</sub> = -30μA	V <sub>CC</sub> - 0.7			V
V <sub>OH1</sub>	Output high voltage (port 0 in external bus mode), ALE <sup>9</sup> , PSEN <sup>3</sup>	$V_{CC} = 2.7V$ $I_{OH} = -3.2$ mA	V <sub>CC</sub> - 0.7			V
I <sub>IL</sub>	Logical 0 input current, ports 1, 2, 3	V <sub>IN</sub> = 0.4V	-1		-50	μΑ
I <sub>TL</sub>	Logical 1-to-0 transition current, ports 1, 2, 3 <sup>6</sup>	V <sub>IN</sub> = 2.0V See note 4			-650	μΑ
I <sub>LI</sub>	Input leakage current, port 0	$0.45 < V_{IN} < V_{CC} - 0.3$			±10	μΑ
Icc	Power supply current (see Figure 36): Active mode @ 16MHz (all except 8XC51RD+) 87C51RD+ Idle mode @ 16MHz Power-down mode or clock stopped (see Figure 40 for conditions)	See note 5 $T_{amb} = 0^{\circ}C \text{ to } 70^{\circ}C$ $T_{amb} = -40^{\circ}C \text{ to } +85^{\circ}C$		3	15 16 4 50 75	mA mA mA μA μA
R <sub>RST</sub>	Internal reset pull-down resistor		40		225	kΩ
C <sub>IO</sub>	Pin capacitance <sup>10</sup> (except EA)				15	pF

- 1. Typical ratings are not guaranteed. The values listed are at room temperature, 5V.
- 2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the Vols of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. IoL can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
- Capacitive loading on ports 0 and 2 may cause the VOH on ALE and PSEN to momentarily fall below the VCC-0.7 specification when the address bits are stabilizing.
- Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V<sub>IN</sub> is approximately 2V.

See Figures 37 through  $^4$ 0 for  $I_{CC}$  test conditions, and Figure 36 for  $I_{CC}$  vs Freq. Active mode:  $I_{CC} = (0.9 \times \text{FREQ.} + 1.1) \text{mA}$  for all devices except 8XC51RD+; 8XC51RD+  $I_{CC} = (0.9 \times \text{Freq} + 2.1) \text{ mA}$ Idle mode:  $I_{CC} = (0.18 \times FREQ. +1.01) mA$ 

- 6. This value applies to T<sub>amb</sub> = 0°C to +70°C. For T<sub>amb</sub> = -40°C to +85°C, I<sub>TL</sub> = -750μA.
   7. Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
- 8. Under steady state (non-transient) conditions, I<sub>OL</sub> must be externally limited as follows: 15mA (\*NOTE: This is 85°C specification.)

Maximum I<sub>OL</sub> per port pin: Maximum I<sub>OL</sub> per 8-bit port: 26mA Maximum total I<sub>OL</sub> for all outputs: 71mA

If I<sub>OL</sub> exceeds the test condition, V<sub>OL</sub> may exceed the related specification. Pins are not guaranteed to sink current greater than the listed

- 9. ALE is tested to V<sub>OH1</sub>, except when ALE is off then V<sub>OH</sub> is the voltage specification.
- 10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25pF. Pin capacitance of ceramic package is less than 15pF (except EA is 25pF).

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMIess, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

### **AC ELECTRICAL CHARACTERISTICS**

 $T_{amb} = 0$ °C to +70°C or -40°C to +85°C,  $V_{CC} = 5V \pm 10\%$ ,  $V_{SS} = 0V^{1, 2, 3}$ 

<u> </u>			VARIABL	33MHz				
SYMBOL	FIGURE	PARAMETER	MIN	MAX	MIN	MAX	UNIT	
t <sub>LHLL</sub>	29	ALE pulse width	2t <sub>CLCL</sub> -40		21		ns	
t <sub>AVLL</sub>	29	Address valid to ALE low	t <sub>CLCL</sub> -25		5		ns	
t <sub>LLAX</sub>	29	Address hold after ALE low	t <sub>CLCL</sub> -25				ns	
t <sub>LLIV</sub>	29	ALE low to valid instruction in		4t <sub>CLCL</sub> -65		55	ns	
t <sub>LLPL</sub>	29	ALE low to PSEN low	t <sub>CLCL</sub> -25		5		ns	
t <sub>PLPH</sub>	29	PSEN pulse width	3t <sub>CLCL</sub> -45		45		ns	
t <sub>PLIV</sub>	29	PSEN low to valid instruction in		3t <sub>CLCL</sub> -60		30	ns	
t <sub>PXIX</sub>	29	Input instruction hold after PSEN	0		0		ns	
t <sub>PXIZ</sub>	29	Input instruction float after PSEN		t <sub>CLCL</sub> -25		5	ns	
t <sub>AVIV</sub>	29	Address to valid instruction in		5t <sub>CLCL</sub> -80		70	ns	
t <sub>PLAZ</sub>	29	PSEN low to address float		10		10	ns	
Data Memor	y	•	•		•		•	
t <sub>RLRH</sub>	30, 31	RD pulse width	6t <sub>CLCL</sub> -100		82		ns	
t <sub>WLWH</sub>	30, 31	WR pulse width	6t <sub>CLCL</sub> -100		82		ns	
t <sub>RLDV</sub>	30, 31	RD low to valid data in		5t <sub>CLCL</sub> -90		60	ns	
t <sub>RHDX</sub>	30, 31	Data hold after RD	0		0		ns	
t <sub>RHDZ</sub>	30, 31	Data float after RD		2t <sub>CLCL</sub> -28		32	ns	
t <sub>LLDV</sub>	30, 31	ALE low to valid data in		8t <sub>CLCL</sub> -150		90	ns	
t <sub>AVDV</sub>	30, 31	Address to valid data in		9t <sub>CLCL</sub> -165		105	ns	
t <sub>LLWL</sub>	30, 31	ALE low to RD or WR low	3t <sub>CLCL</sub> -50	3t <sub>CLCL</sub> +50	40	140	ns	
t <sub>AVWL</sub>	30, 31	Address valid to WR low or RD low	4t <sub>CLCL</sub> -75		45		ns	
t <sub>QVWX</sub>	30, 31	Data valid to WR transition	t <sub>CLCL</sub> -30		0		ns	
t <sub>WHQX</sub>	30, 31	Data hold after WR	t <sub>CLCL</sub> -25		5		ns	
t <sub>QVWH</sub>	31	Data valid to WR high	7t <sub>CLCL</sub> -130		80		ns	
t <sub>RLAZ</sub>	30, 31	RD low to address float		0		0	ns	
t <sub>WHLH</sub>	30, 31	RD or WR high to ALE high	t <sub>CLCL</sub> -25	t <sub>CLCL</sub> +25	5	55	ns	
External Clo	ck	-						
t <sub>CHCX</sub>	33	High time	0.38t <sub>CLCL</sub>	t <sub>CLCL</sub> -t <sub>CLCX</sub>			ns	
t <sub>CLCX</sub>	33	Low time	0.38t <sub>CLCL</sub>	tclcl-tchcx			ns	
tclch	33	Rise time		5			ns	
t <sub>CHCL</sub>	33	Fall time		5			ns	
Shift Regist	er		_					
$t_{XLXL}$	32	Serial port clock cycle time	12t <sub>CLCL</sub>		360		ns	
t <sub>QVXH</sub>	32	Output data setup to clock rising edge	10t <sub>CLCL</sub> -133		167		ns	
t <sub>XHQX</sub>	32	Output data hold after clock rising edge	2t <sub>CLCL</sub> -80				ns	
t <sub>XHDX</sub>	32	Input data hold after clock rising edge	0		0		ns	
t <sub>XHDV</sub>	32	Clock rising edge to input data valid		10t <sub>CLCL</sub> -133		167	ns	

- Parameters are valid over operating temperature range unless otherwise specified.
   Load capacitance for port 0, ALE, and PSEN = 100pF, load capacitance for all other outputs = 80pF.
   Interfacing the microcontroller to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0
- 4. For frequencies equal or less than 16MHz, see 16MHz "AC Electrical Characteristics", page 38.
- 5. Parts are guaranteed to operate down to 0Hz.

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

**Table 9. EPROM Programming Modes** 

MODE	RST	PSEN	ALE/PROG	EA/V <sub>PP</sub>	P2.7	P2.6	P3.7	P3.6
Read signature	1	0	1	1	0	0	0	0
Program code data	1	0	0*	V <sub>PP</sub>	1	0	1	1
Verify code data	1	0	1	1	0	0	1	1
Pgm encryption table	1	0	0*	V <sub>PP</sub>	1	0	1	0
Pgm security bit 1	1	0	0*	$V_{PP}$	1	1	1	1
Pgm security bit 2	1	0	0*	$V_{PP}$	1	1	0	0
Pgm security bit 3	1	0	0*	$V_{PP}$	0	1	0	1

### NOTES:

- 1. '0' = Valid low for that pin, '1' = valid high for that pin.

V<sub>PP</sub> = 12.75V ±0.25V.
 V<sub>CC</sub> = 5V±10% during programming and verification.

Table 10. Program Security Bits for EPROM Devices

PROGRAM LOCK BITS <sup>1, 2</sup>			31, 2	
	SB1	SB2	SB3	PROTECTION DESCRIPTION
1	U	U	U	No Program Security features enabled. (Code verify will still be encrypted by the Encryption Array if programmed.)
2	Р	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on Reset, and further programming of the EPROM is disabled.
3	Р	Р	U	Same as 2, also verify is disabled.
4	Р	Р	Р	Same as 3, external execution is disabled.

#### NOTES:

- 1. P programmed. U unprogrammed.
- 2. Any other combination of the security bits is not defined.

ALE/PROG receives 5 programming pulses for code data (also for user array; 5 pulses for encryption or security bits) while V<sub>PP</sub> is held at 12.75V. Each programming pulse is low for 100μs (±10μs) and high for a minimum of 10μs.

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

## ROM CODE SUBMISSION FOR 16K ROM DEVICES (80C54, 83C51FB AND 83C51RB+)

When submitting ROM code for the 16K ROM devices, the following must be specified:

- 1. 16k byte user ROM data
- 2. 64 byte ROM encryption key
- 3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 3FFFH	DATA	7:0	User ROM Data
4000H to 403FH	KEY	7:0	ROM Encryption Key FFH = no encryption
4040H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
4040H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

- 1. External MOVC is disabled, and
- 2. EA is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

NOTE: Security Bit 2 cannot be enabled unless Security Bit 1 is enabled.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1:	☐ Enabled	☐ Disabled
Security Bit #2:	☐ Enabled	☐ Disabled
Encryption:	□ No	☐ Yes If Yes, must send key file.

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

## ROM CODE SUBMISSION FOR 32K ROM DEVICES (80C58, 83C51FC, AND 83C51RC+)

When submitting ROM code for the 32K ROM devices, the following must be specified:

- 1. 32k byte user ROM data
- 2. 64 byte ROM encryption key
- 3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 7FFFH	DATA	7:0	User ROM Data
8000H to 803FH	KEY	7:0	ROM Encryption Key FFH = no encryption
8040H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
8040H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

- 1. External MOVC is disabled, and
- 2. EA is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

NOTE: Security Bit 2 cannot be enabled unless Security Bit 1 is enabled.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1:	☐ Enabled	☐ Disabled
Security Bit #2:	☐ Enabled	☐ Disabled
Encryption:	□ No	☐ Yes If Yes, must send key file.

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

# ROM CODE SUBMISSION FOR 64K ROM DEVICE (83C51RD+)

When submitting ROM code for the 64K ROM devices, the following must be specified:

- 1. 64k byte user ROM data
- 2. 64 byte ROM encryption key
- 3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to FFFFH	DATA	7:0	User ROM Data
10000H to 1003FH	KEY	7:0	ROM Encryption Key FFH = no encryption
10040H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
10040H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

- 1. External MOVC is disabled, and
- 2. EA is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

NOTE: Security Bit 2 cannot be enabled unless Security Bit 1 is enabled.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

For each of the following, check the appropriate box, and send to Philips along with the code:

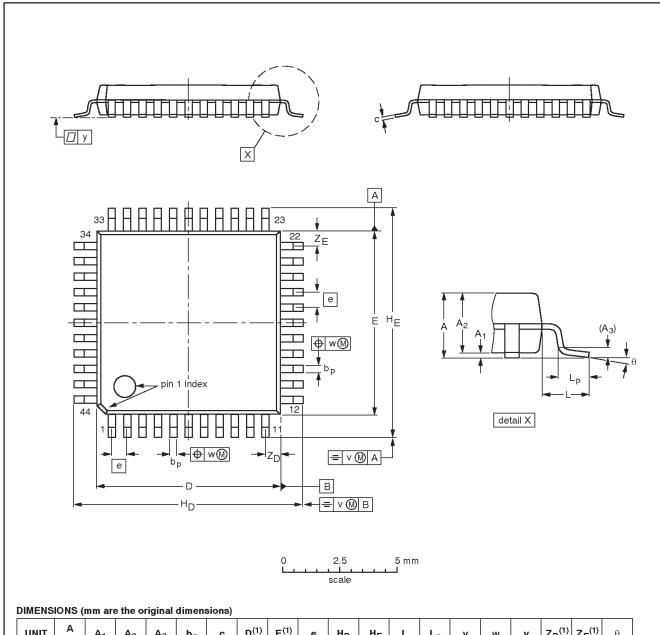
Security Bit #1:	☐ Enabled	☐ Disabled
Security Bit #2:	☐ Enabled	☐ Disabled
Encryption:	□ No	☐ Yes If Yes, must send

80C51 8-bit microcontroller family 8K-64K/256-1K OTP/ROM/ROMless, low voltage (2.7V-5.5V), low power, high speed (33MHz)

8XC54/58 8XC51FA/FB/FC/80C51FA 8XC51RA+/RB+/RC+/RD+/80C51RA+

# QFP44: plastic quad flat package; 44 leads (lead length 1.3 mm); body 10 x 10 x 1.75 mm

SOT307-2



UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	Ьp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	H <sub>D</sub>	HE	L	Lp	v	w	у	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	2.10	0.25 0.05	1.85 1.65	0.25	0.40 0.20	0.25 0.14	10.1 9.9	10.1 9.9	0.8	12.9 12.3	12.9 12.3	1.3	0.95 0.55	0.15	0.15	0.1	1.2 0.8	1.2 0.8	10° 0°

# Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFEF	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT307-2						<del>-95-02-04</del> 97-08-01	